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### ON Semiconductor®

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December 2015

## FQT4N25TF N-Channel QFET® MOSFET

250 V, 0.83 A, 1.75  $\Omega$ 

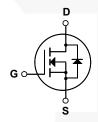
#### **Description**

This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor®'s proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.

#### **Features**

- 0.83 A, 250 V,  $R_{DS(on)}$ =1.75  $\Omega(Max.)$ @ $V_{GS}$ =10 V,  $I_D$ =0.415 A
- Low Gate Charge (Typ. 4.3 nC)
- Low C<sub>rss</sub> (Typ. 4.8 pF)





### **Absolute Maximum Ratings** $T_C = 25$ °C unless otherwise noted

Symbol	Parameter		FQT4N25TF	Unit
V <sub>DSS</sub>	Drain-Source Voltage		250	V
$I_D$	Drain Current - Continuous (T <sub>C</sub> = 25°C) - Continuous (T <sub>C</sub> = 70°C)		0.83	Α
			0.66	Α
I <sub>DM</sub>	Drain Current - Pulsed	(Note 1)	3.3	А
V <sub>GSS</sub>	Gate-Source Voltage		± 30	V
E <sub>AS</sub>	Single Pulsed Avalanche Energy	(Note 2)	52	mJ
I <sub>AR</sub>	Avalanche Current	(Note 1)	0.83	А
E <sub>AR</sub>	Repetitive Avalanche Energy	(Note 1)	0.25	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	5.5	V/ns
$P_{D}$	Power Dissipation (T <sub>C</sub> = 25°C) - Derate above 25°C		2.5	W
			0.02	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150	°C
T <sub>L</sub>	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C

#### **Thermal Characteristics**

Symbol	Parameter	Тур	Max	Unit
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *		50	°C/W

<sup>\*</sup> When mounted on the minimum pad size recommended (PCB Mount)

### **Package Marking and Ordering Information**

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQT4N25TF	FQT4N25	SOT-223	Tape and Reel	13"	12 mm	2500 units

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
Off Cha	racteristics					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	250			V
ΔBV <sub>DSS</sub> / ΔΤ <sub>J</sub>	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$ , Referenced to 25°C		0.22		V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 250 V, V <sub>GS</sub> = 0 V			1	μΑ
		V <sub>DS</sub> = 200 V, T <sub>C</sub> = 125°C			10	μΑ
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V			100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
On Cha	racteristics					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	3.0		5.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 0.415 A		1.38	1.75	Ω
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 50 V, I <sub>D</sub> = 0.415 A (Note 4)		1.28		S
Dynami	c Characteristics					
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V,		155	200	pF
C <sub>oss</sub>	Output Capacitance	f = 1.0 MHz		35	45	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			4.8	6.5	pF
Switchi	ng Characteristics					
t <sub>d(on)</sub>	Turn-On Delay Time	V - 135 V I - 2 6 A		6.8	25	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{DD} = 125 \text{ V}, I_{D} = 3.6 \text{ A},$ $R_{G} = 25 \Omega$		45	100	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	NG - 25 32	/	6.4	25	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4, 5)		22	55	ns
Q <sub>q</sub>	Total Gate Charge	V <sub>DS</sub> = 200 V, I <sub>D</sub> = 3.6 A,		4.3	5.6	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> = 10 V		1.3		nC
Q <sub>gd</sub>	Gate-Drain Charge	(Note 4, 5)		2.1		nC
	ource Diode Characteristics a	nd Maximum Ratings				
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current			//	0.83	Α
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current				3.3	Α
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = 0.83 \text{ A}$		\	1.5	V
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0 \text{ V, } I_S = 3.6 \text{ A,}$		110		ns

 $dI_F / dt = 100 A/\mu s$ 

(Note 4)

0.35

## $Q_{rr}$

- Notes: Notes: 1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 120mH, I $_{AS}$  = 0.83A, V $_{DD}$  = 50V, R $_{G}$  = 25  $_{QS}$  Starting T $_{J}$  = 25°C 3. I $_{SD}$  ≤ 3.6A, di/dt ≤ 300A/µs, V $_{DD}$  ≤ BV $_{DSS}$ , Starting T $_{J}$  = 25°C 4. Pulse Test : Pulse width ≤ 300µs, Duty cycle ≤ 2% 5. Essentially independent of operating temperature

Reverse Recovery Charge

μС

# Typical Characteristics

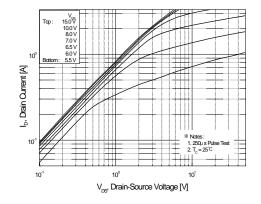


Figure 1. On-Region Characteristics

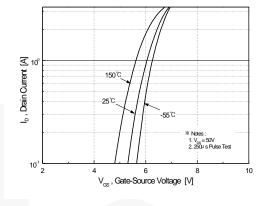


Figure 2. Transfer Characteristics

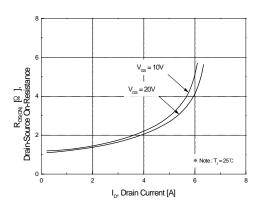


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

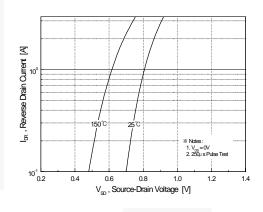


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

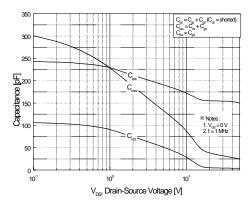


Figure 5. Capacitance Characteristics

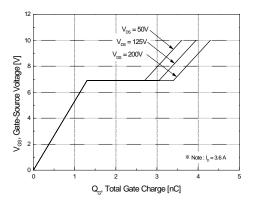
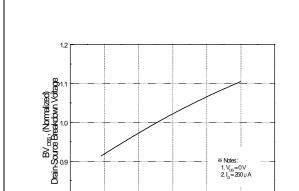


Figure 6. Gate Charge Characteristics



Typical Characteristics (Continued)

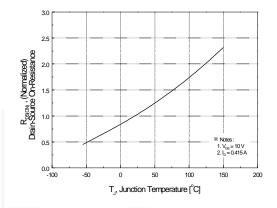
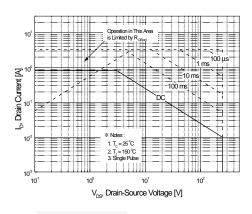


Figure 7. Breakdown Voltage Variation vs. Temperature

T\_, Junction Temperature [°C]

Figure 8. On-Resistance Variation vs. Temperature



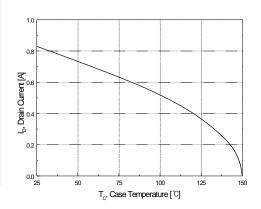


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

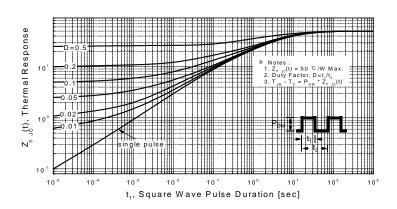
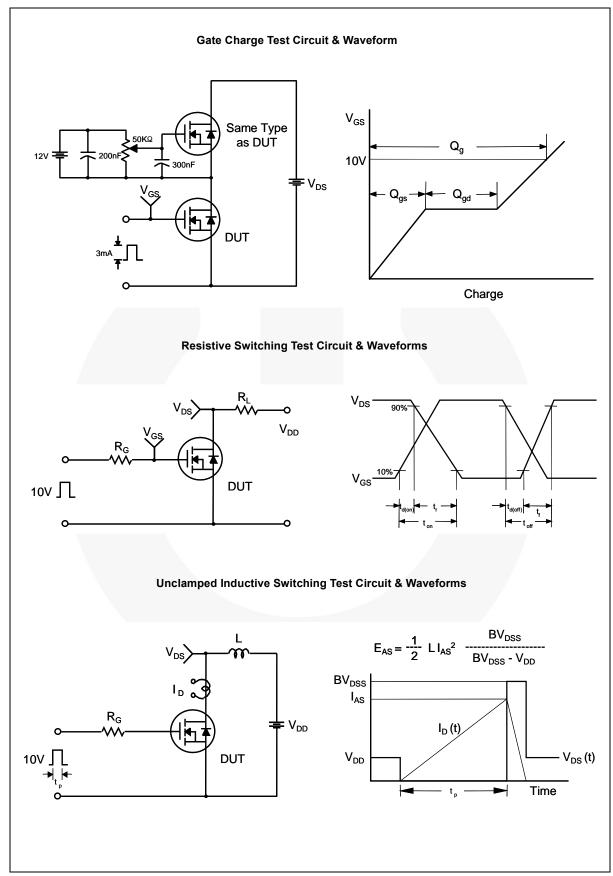
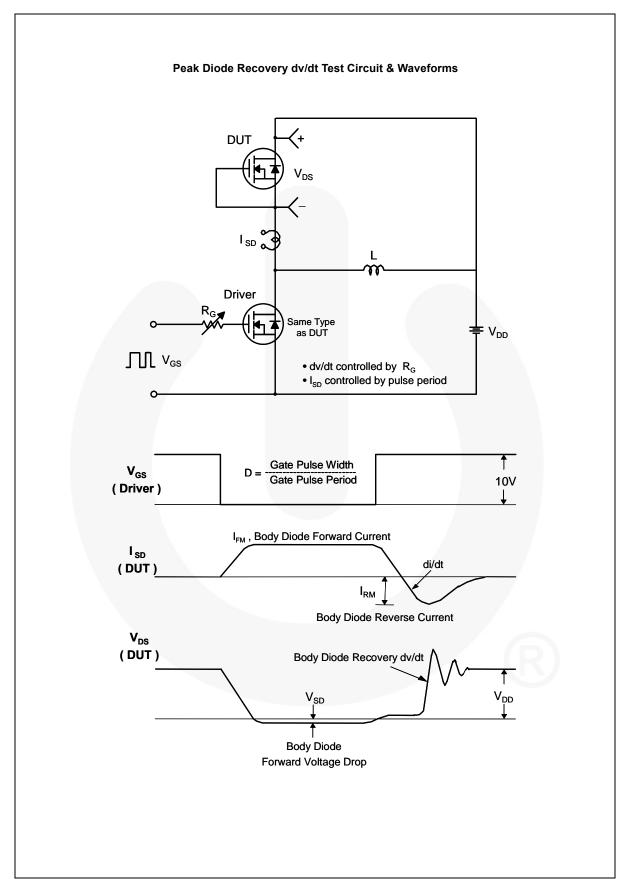
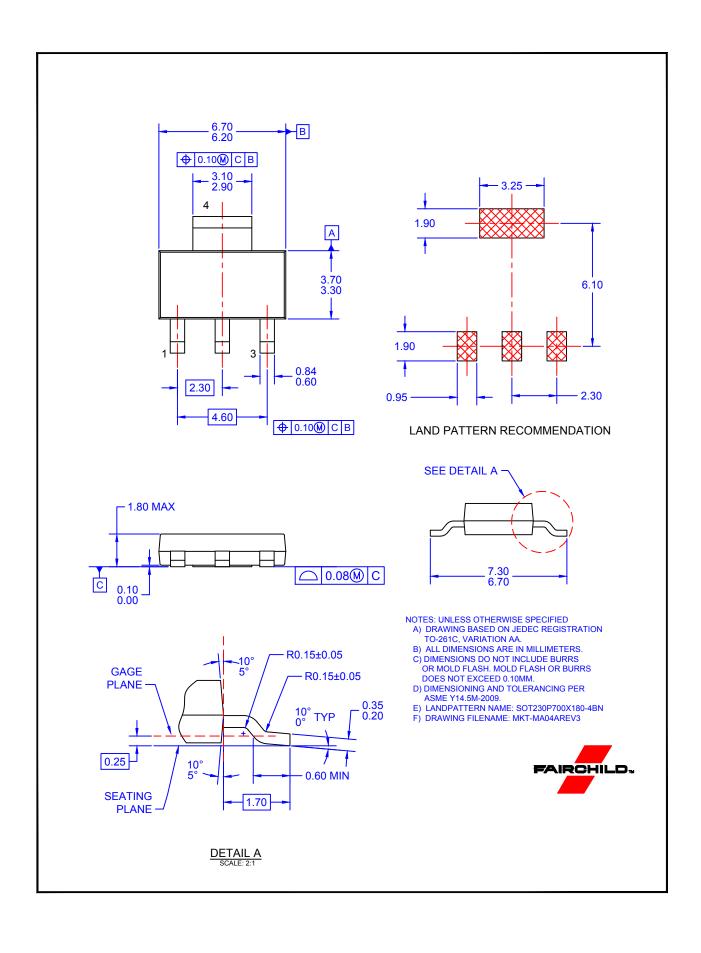


Figure 11. Transient Thermal Response Curve







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